

ABSTRACT

The present disclosure provides a polishing head, a substrate polishing device and a grinding method. The polishing head includes: a main body; a suction holding component fixed to a bottom centre of the main body for sucking a substrate and pressing the substrate on a polishing surface; and an edge force exerting component on outer peripheral side of the suction holding component and below the main body, wherein the edge force exerting component has a bottom wall for pressing on edge area of the substrate to adjust polishing pressure on the edge area of the substrate. Through the edge force exerting component, the amount of grinding at the edge of the substrate may be adjusted. Besides, the suction holding component is also provided, and by adjusting the gas pressure in each ventilation groove and each closed suction chamber connected thereto, the amount of grinding in the central part of the substrate may be adjusted. Thus, the uniformity and consistency of the substrate surface may be improved, thereby achieving high planarization.

[Fig. 1]